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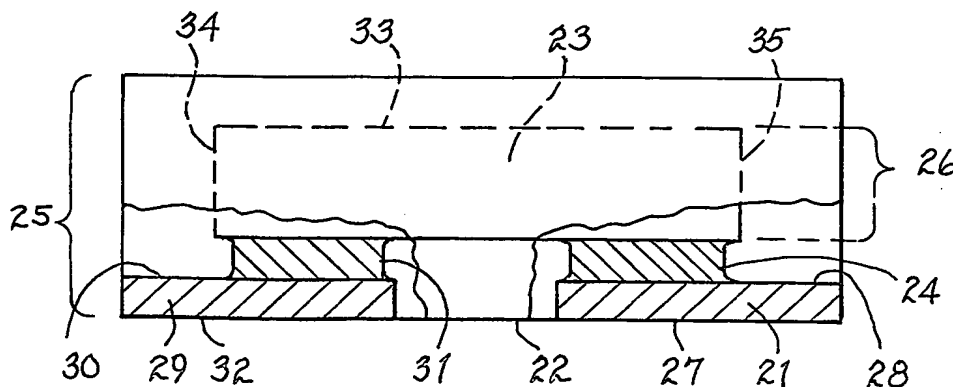
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**(54) Title:** LOW PROFILE SMALL OUTLINE LEADLESS SEMICONDUCTOR DEVICE PACKAGE



**(S7) Abstract:** A molded leadless package encapsulates a small outline integrated circuit or small outline transistor through contact bumps. Electrical contacts extend from the encapsulated device to an exposed surface of the package and are coplanar with that surface and terminate at a junction between said surface at a junction with another of the package surfaces. The contacts terminate only at oppositely disposed surfaces of the package.

**WO 2004/093135 A2**